Tuesday, March 28 - Workshops

8:30am - 12:00pm	**WS1** Robust Coating Processes in the Factory: Methods, Critical Parameters, Problems and Remedies *Instructor: Jason Keeping, P.Eng. Celestica, Inc.*	**WS2** Choosing Solders for the New Era Part 1- Low Cost High Reliability Lead-Free Solder Alloys *Instructor: Ning-Cheng Lee, Ph.D., Indium Corporation*
1:30pm 5:00pm	**WS3** Fan-Out Wafer-Level Packaging and 3D Packaging *Instructor: John Lau, Ph.D., ASM Pacific Technology*	**WS4** Choosing Solders for the New Era Part 2- It is Time for Low Temperature: Low Temperature Solders, New Development, and Their Applications *Instructor: Ning-Cheng Lee, Ph.D., Indium Corporation*
Location	Olive 4	Olive 5

Wednesday, March 29 – Technical Program

7:30am	**Registration**	**Speaker**
8:50am	**Opening Comments**	Feon Chow, Agilent Technologies
	Session 1: Cleaning of No Clean Flux Residues	Session Chair: Feon Chow Agilent Technologies
9:00am	Cleaning Lead-Free No-Clean PCBA to Improve ICT Probe Contact Rate	KongHui Lee, Ph.D., CSMTPE Cisco Systems (Malaysia) Sdn. Bhd.
9:30am	Cleanability and Reliability Study of No Clean Chemistries for Lead Free Solder Paste in Vapour Phase Reflow	Weihang (Steven) Teh Inventec Performance Chemicals SEA Sdn. Bhd.
10:00am	**Refreshment Break**	
	Session 2: Cleaning Challenges for Board Assemblies	Session Chair: KongHui Lee, Ph.D., CSMTPE Cisco Systems (Malaysia) Sdn. Bhd.
10:30am	Development of a Risk Profile from Flux Residues Trapped under Leadless Components	Bruno Tolla, Ph.D., KESTER Corporation
11:00am	Impact of Multiple Thermal Cycles on the Cleaning Process	Guan Tatt Yeoh ZESTRON Precision Cleaning Sdn. Bhd.
11:30am	**Keynote Address: When Coating Hits the Fan - Consequences of Poor Ruggedization**	Jason Keeping, P.Eng., Celestica, Inc.
12:30pm	**Lunch**	
	Session 3: Enhancing Assembly and Test Processes	Session Chair: Mei-Ming Khaw Keysight Technologies
1:30pm	Air Plasma at Atmospheric-Pressure for Improving Conformal Coating Reliability	Mathieu Gonsolin, eXelsius
2:00pm	A Shift Left and Predictive Approach in Test Quality Management	Feng Xue, IBM Corporation
2:30pm	SiP Package Defect Case Study- Tombstone and HIP	Jason Chou Sheng-Hung, P.E. Indium Corporation
3:00pm	Flip-Chip LED Assembly – Processes and Challenges	Gyan Dutt, Alpha Assembly Solutions
3:30pm	**Refreshment Break**	

	Session 4: Design and Manufacturing	Session Chair: Gyan Dutt Alpha Assembly Solutions
4:00pm	Assessment of Solder Paste Technology Limitation for Printing Applications	Ning-Cheng Lee, Ph.D. Indium Corporation
4:30pm	The Effects of Board Design on Electroplated Copper Filled Thermal Vias for Heat Management	Richard Bellemare MacDermid Enthone Electronics Solutions
5:00pm	Voiding Control at LED Die Attach Preform Soldering	Ning-Cheng Lee, Ph.D., Indium Corporation
5:30pm	Impact of Interconnects for LEDs on Flexible Substrates	Amit Patel, Alpha Assembly Solutions
6:00pm	**Penang 10th Anniversary Celebration**	

Thursday, March 30 – Technical Program

8:00am	**Registration**	**Speaker**
	Session 5: Advanced Packaging	Session Chair: Jonas Sjoberg Indium Corporation
9:00am	What's Moore to Advanced Packaging	John Almirañez Universal Instruments Corporation
9:30am	System-in-Package (SiP) Assembly vs. Solder Paste Attributes	Kenneth Thum, Indium Corporation
10:00am	**Keynote Address: Advanced Semiconductor IC Packaging**	John Lau, Ph.D., ASM Pacific Technology
11:00am	**Refreshment Break**	
	Session 6: Inspection and Quality	Session Chair: Yee May Koh Keysight Technologies
11:30am	A Data Analytics Approach to Managing IBM Storage Field Quality	Feng Xue, IBM Corporation
12:00pm	Functional Failure Reduction and End Product Field Reliability Improvement through PCBA Cleaning Optimization	Harwin Kaur Karban Singh Celestica (M) Sdn. Bhd.
12:30pm	The Basics of Todays X-Ray Technology	Justin Kow, YXLON International GmbH
1:00pm	**Lunch**	
	Session 7: IoT Manufacturing Considerations	Session Chair: KL Lim, Plexus Corp.
2:00pm	Requirements for a Secure and Scalable Industrial Internet of Things (IIoT) Platform for the PCB Assembly Industry to Achieve a Smart Factory	Jay Gorajia, Mentor Graphics
2:30pm	**Keynote Address: IoE – Next Generation Supply Chain Ecosystems**	Nasrudin Bin Abdul Muthalib Cisco Systems (Malaysia) Sdn. Bhd.
3:30pm	**Refreshment Break**	
	Session 8: Paste Printing and Soldering	Session Chair: Wesley Khoo, Plexus Corp.
3:45pm	Soldering Immersion Tin	Rick Nichols Atotech Deutschland GmbH
4:15pm	Stencil Printing Techniques for Metric 0201's In A Heterogeneous Assembly Environment	Mark Whitmore ASM Assembly Systems
4:45pm	**Conference Conclusion**	

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